

SOT545-1

plastic thermal enhanced thin quad flat package; 48 leads;
body 7 x 7 x 1 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP48
Package type industry code	HTQFP48
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	29-1-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	48	-	



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2. Package outline

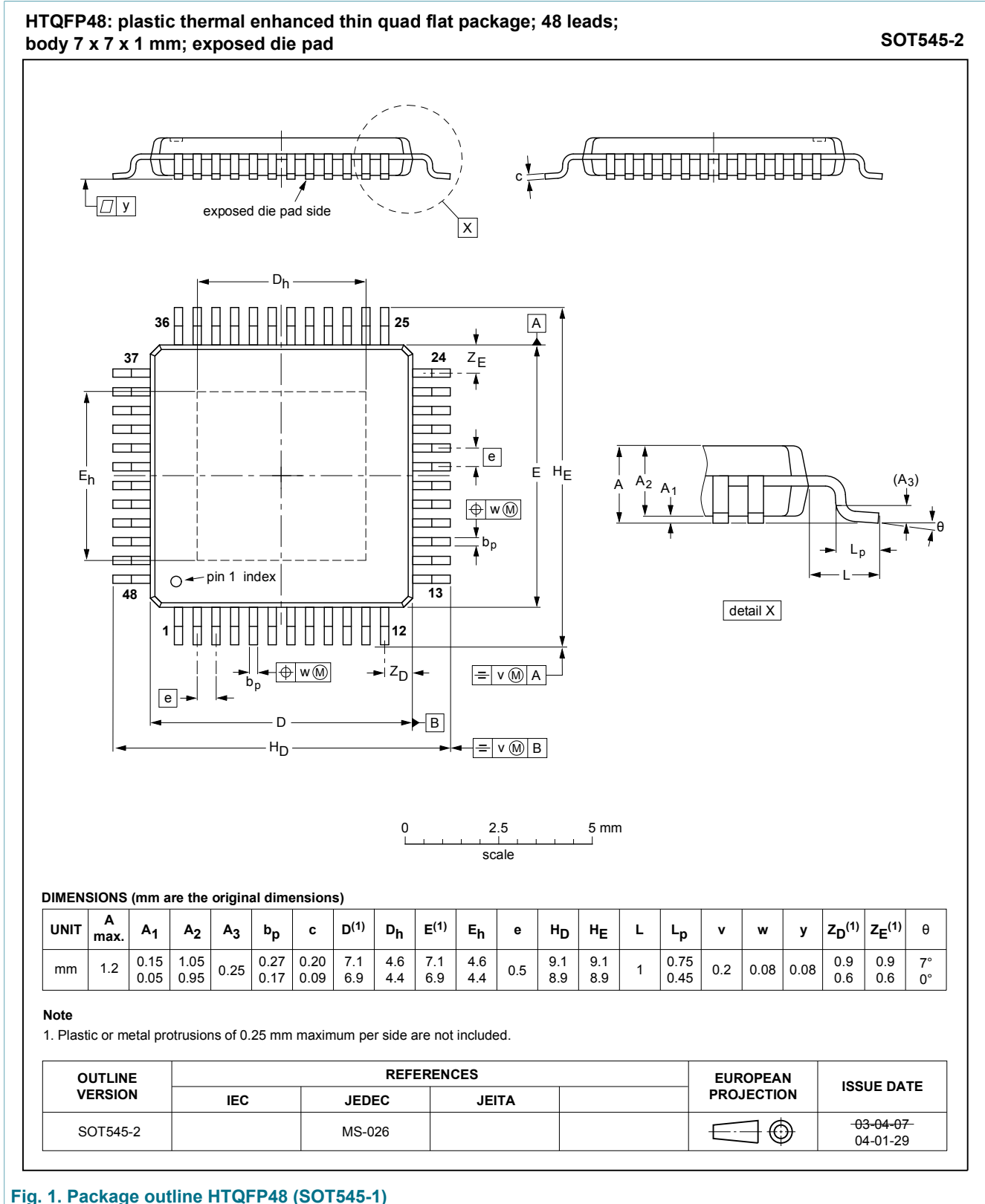


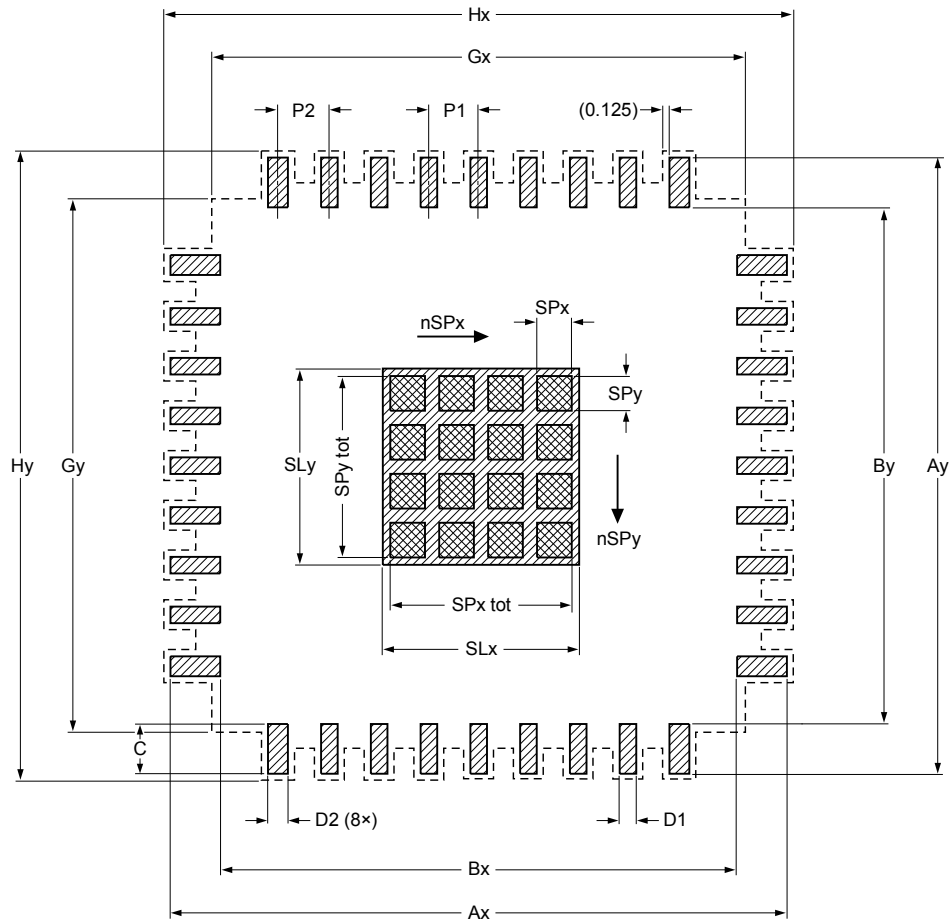
Fig. 1. Package outline HTQFP48 (SOT545-1)

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3. Soldering

Footprint information for reflow soldering of HTQFP48 package

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Generic footprint pattern

Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area

nSPx	nSPy
4	4

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy	SLx	SLy	SPx tot	SPy tot	SPx	SPy		
0.500	0.560	9.700	9.700	7.300	7.300	1.200	0.280	0.400	7.500	7.500	9.950	9.950	5.300	5.300	5.200	5.200	0.900	0.900		
Issue date	09-12-21																	09-12-21	sot545-1_fr	

Fig. 2. Reflow soldering footprint for HTQFP48 (SOT545-1)

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4. Legal information

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